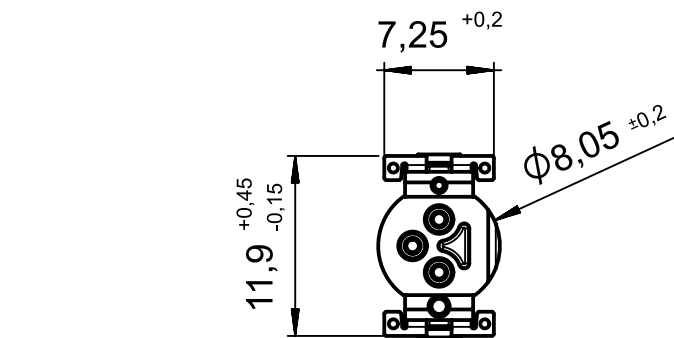
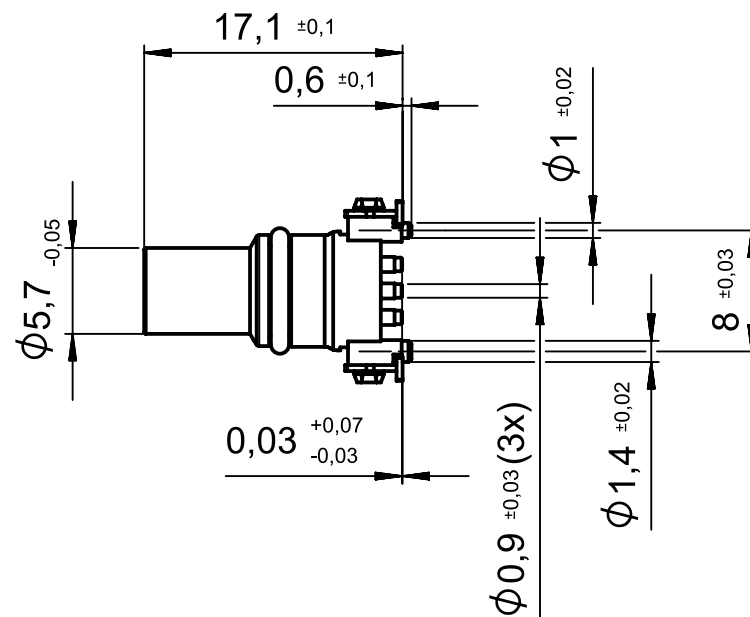
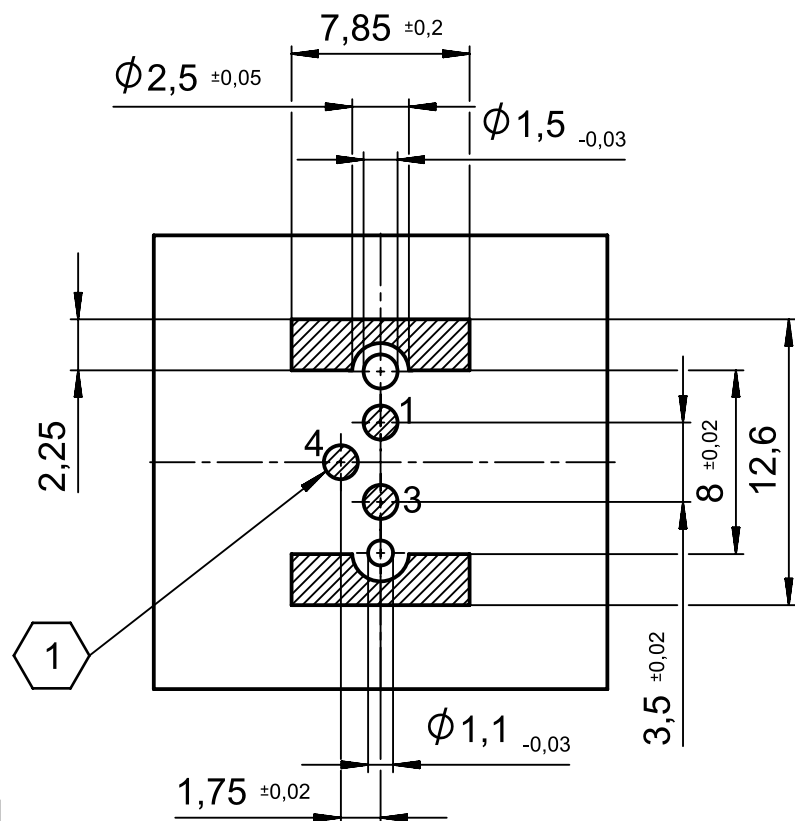


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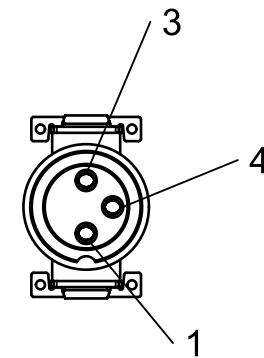
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PCB-layout
(advice)



socket face female



Coplanarity of all contacts and anchor plate  0.1

Recommended solder paste thickness 150µm

1 Further information on soldering process and recommended layout,
see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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page	1	of	1		

A3